ASSOCIATION CONNE	Material Comp © Copyright 2005. I international and Pa	© Converight 2005 TPC Rannockburn Illinois All rights reserved under both				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.								
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				*	Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information								
Supplier Info	ormation													
Company name* Company unique ID					τ	Unique ID Authority				Response Date*				
nsemi				2024-05-0						1-05-05				
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*			
Product-Env-St	tewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative* Title - R			Title - Repres	sentative	ative]			Phone - Representative*			Email - Representative*			
Product-Env-Stewards Product Enviro Compliance					NA Product-Env-Stewards@onsemi.com					om				
Requ	uester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	N	Manufacturing Site		Weight*	UOM	Unit Type
		AR0220. A1-TRB	AT4R00XUE M	2MP 1/2 CIS SO			2024-05-05		7	ïWU	:	298.74	mg	Each
Ianufacturi	ng Proccess Informa	ition												
Terminal Plating / Grid Array Material Terminal Base Alloy J-STD-020 MSI					L Rating	Peak Proc	ess Body T	emperatur	e Max Time at Peak	Temperat	ure Numb	er of Reflow Cyc	eles	
SnAgCu CU Alloy				3		260		С	30	secon	ds 3			
omments														
TTENTION: N	MSL 3 Rated item require	es Bake and D	ry Pack (after	electrical test)										
or more inform	nation regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct at it in member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	62.85	mg		Misc.	proprietary data		0.2388	mg
			Supplier	Silicon (Si)	7440-21-3		61.989	mg
			Supplier	Aluminum (Al)	7429-90-5		0.6222	mg
Die Attach	3.83	mg		Bismaleimide Monomer	proprietary data		1.4745	mg
			Supplier	POLY(ETHYLENE GLYCOL) PHENYL ETHER ACRYLATE	56641-05-5		0.0192	mg
			Supplier	2,2-Bis(4-hydroxyphenyl)propane- epichlorohydrin copolymer acrylate	55818-57-0		0.383	mg
			Supplier	Bis(4-tert-butylcyclohexyl) peroxydicarbonate	15520-11-3		0.0192	mg
			Supplier	2,2-dimethyl-1,3-propanediyl dimethacrylate	1985-51-9		0.383	mg
			Supplier	2-phenoxy ethyl acrylate	48145-04-6		0.383	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.0192	mg
			Supplier	Other Additive Agents	Proprietary Data		0.766	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.383	mg
Epoxy	1.83	mg	Supplier	Imidazole Addition	68490-66-4		0.549	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.183	mg
			Supplier	Zirconium Dioxide (ZrO2)	1314-23-4		0.183	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.183	mg
			Supplier	Formaldehyde Polymer	9003-36-5		0.732	mg
Imaging Lens	55.66	mg	Supplier	Titanium Dioxide (TiO2)	13463-67-7		2.783	mg
			Supplier	Sodium Monoxide (Na2O)	1313-59-3		2.783	mg
			Supplier	Boron Trioxide (B2O3)	1303-86-2		2.783	mg
			Supplier	Zinc Monoxide (ZnO)	1314-13-2		2.783	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		0.2783	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.783	mg
			Supplier	Potassium Monoxide (K2O)	12136-45-7		2.783	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		38.6837	mg
Mold Compound	72.64	mg		Epoxy resin	proprietary data		18.0147	mg
			Supplier	Other Additive Agents	Proprietary Data		2.3245	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		7.264	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		42.8576	mg

			Supplier	Silica Crystalline (SiO2)	14808-60-7	2.1792	mg
Passivation	0.3	mg	Supplier	Dimethylsilicone	63148-62-9	0.015	mg
			Supplier	Organic pigment	Proprietary Data	0.03	mg
			Supplier	Other Epoxy resins	Proprietary Data	0.255	mg
Solder Ball	49.42	mg	Supplier	Silver (Ag)	7440-22-4	1.4826	mg
			Supplier	Tin (Sn)	7440-31-5	47.6903	mg
			Supplier	Copper (Cu)	7440-50-8	0.2471	mg
Solder Mask	5.605	mg		Epoxy resin	proprietary data	0.6726	mg
			Supplier	Acrylate	Proprietary Data	2.1411	mg
			Supplier	Talc	14807-96-6	0.1513	mg
			Supplier	Miscellaneous	Trade Secret	0.2074	mg
			Supplier	Barium Sulfate (BaSO4)	7727-43-7	2.4326	mg
Substrate Copper Foil	4.313	mg	Supplier	Copper (Cu)	7440-50-8	4.313	mg
Substrate - Core Material	21.426	mg		Epoxy resin	proprietary data	4.643	mg
			Supplier	Fiber Glass (SiO2)	65997-17-3	16.783	mg
Substrate Plating-Au	0.371	mg	Supplier	Gold (Au)	7440-57-5	0.371	mg
Substrate Plating-Cu	19.284	mg	Supplier	Copper (Cu)	7440-50-8	19.284	mg
Substrate Plating-Ni	0.891	mg	В	Nickel (Ni)	7440-02-0	0.891	mg
Wire Bond - Au	0.32	mg	Supplier	Gold (Au)	7440-57-5	0.32	mg